

ABSTRACT OF THE DISCLOSURE

An ultrasound transducer assembly is disclosed having a housing, a transducer array mounted in the housing and an electronics assembly mounted in the housing, the electronics assembly including one or more sub-assemblies having heat generating components disposed thereon. The electronics sub-assemblies further include thermal conducting features which conduct heat generated by the heat generating components out of the electronics assembly where it can be further removed by other thermal management techniques. These other thermal management techniques may include techniques utilized to cool the transducer array.